

V_{DSS}	600V
$R_{DS(on)}(Max.)$	0.234Ω
I_D	±20A
P_D	252W

●Features

- 1) Fast reverse recovery time (trr)
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Drive circuits can be simple
- 5) Pb-free plating ; RoHS compliant

●Application

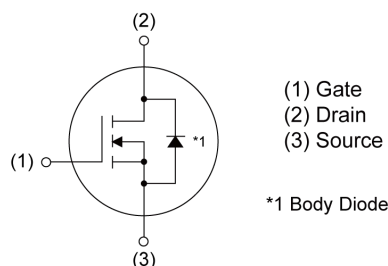
Switching applications

●Outline

LPT(S)



●Inner circuit



●Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6020JNJ
Quantity (pcs)	1000

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	600	V
Continuous drain current ($T_c = 25^\circ\text{C}$)	I_D^{*1}	±20	A
Pulsed drain current	I_{DP}^{*2}	±60	A
Gate - Source voltage	V_{GSS}	±30	V
Avalanche current, single pulse	I_{AS}^{*3}	4.8	A
Avalanche energy, single pulse	E_{AS}^{*3}	618	mJ
Power dissipation ($T_c = 25^\circ\text{C}$)	P_D	252	W
Junction temperature	T_j	150	°C
Operating junction and storage temperature range	T_{stg}	-55 to +150	°C

● Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	R_{thJC}	-	-	0.49	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T_{solder}	-	-	265	°C

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	600	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^\circ\text{C}$	-	-	100	μA
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 600V$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 3.5mA$	5.0	6.0	7.0	V
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	$V_{GS} = 15V, I_D = 10A$ $T_j = 25^\circ\text{C}$	-	0.180	0.234	Ω
Gate resistance	R_G	$f = 1MHz, \text{open drain}$	-	2.0	-	Ω

●Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C_{iss}	$V_{GS} = 0V$	-	1500	-	pF
Output capacitance	C_{oss}	$V_{DS} = 100V$	-	90	-	
Reverse transfer capacitance	C_{rss}	$f = 1\text{MHz}$	-	1.9	-	
Effective output capacitance energy related	$C_{o(er)}^{*6}$	$V_{GS} = 0V$	-	68	-	
Effective output capacitance time related	$C_{o(tr)}^{*7}$	$V_{DS} = 0V \text{ to } 480V$	-	270	-	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \approx 300V, V_{GS} = 15V$	-	29	-	ns
Rise time	t_r^{*5}	$I_D = 10A$	-	22	-	
Turn - off delay time	$t_{d(off)}^{*5}$	$R_L \approx 30.1\Omega$	-	56	-	
Fall time	t_f^{*5}	$R_G = 10\Omega$	-	13	-	

●Gate charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g^{*5}	$V_{DD} \approx 300V$	-	45	-	nC
Gate - Source charge	Q_{gs}^{*5}	$I_D = 20A$	-	15	-	
Gate - Drain charge	Q_{gd}^{*5}	$V_{GS} = 15V$	-	17	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} \approx 300V, I_D = 20A$	-	9.5	-	V

*1 Limited only by maximum temperature allowed.

*2 $P_w \leq 10\mu s$, Duty cycle $\leq 1\%$

*3 $L \approx 50mH$, $V_{DD} = 50V$, $R_G = 25\Omega$, starting $T_j = 25^\circ\text{C}$

*4 $T_c = 25^\circ\text{C}$

*5 Pulsed

*6 $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

*7 $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

●Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Source current	I_S^{*1}	$T_C = 25^\circ\text{C}$	-	-	20	A
Pulsed source current	I_{SP}^{*2}		-	-	60	A
Source-Drain voltage	V_{SD}^{*5}	$V_{GS} = 0\text{V}, I_S = 20\text{A}$	-	-	1.7	V
Reverse recovery time	t_{rr}^{*5}	$I_S = 20\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$	-	85	-	ns
Reverse recovery charge	Q_{rr}^{*5}		-	280	-	nC
Peak reverse recovery current	I_{rr}^{*5}		-	7.5	-	A

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

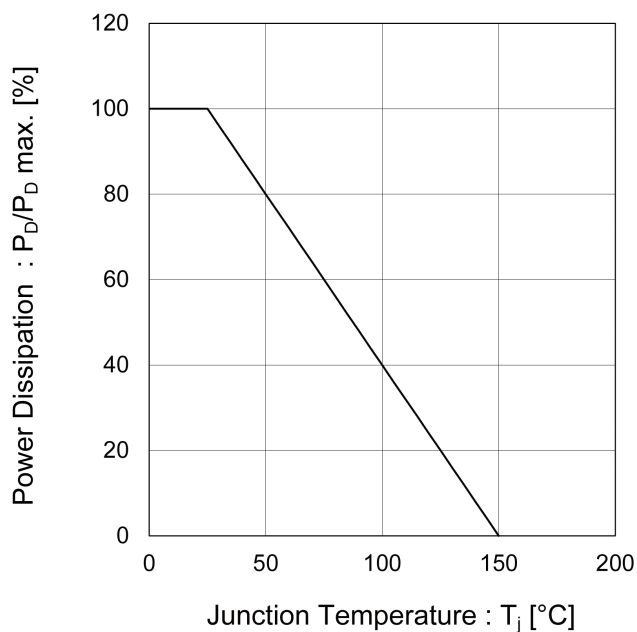


Fig.2 Drain Current Derating Curve vs. Junction Temperature

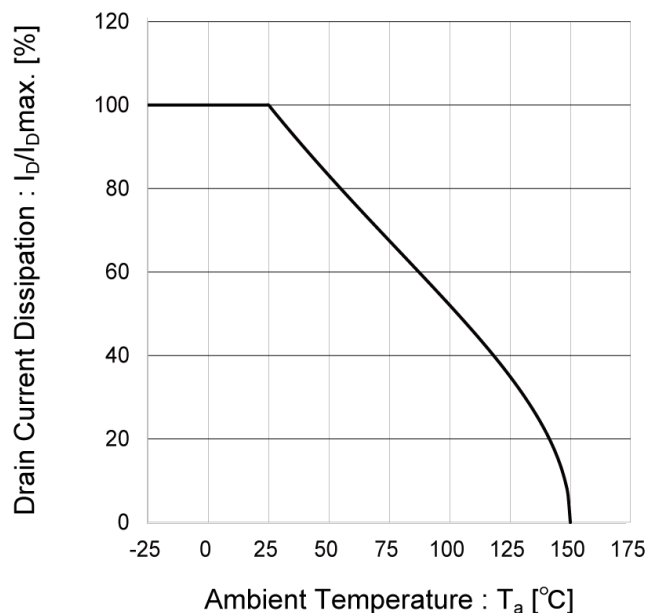


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

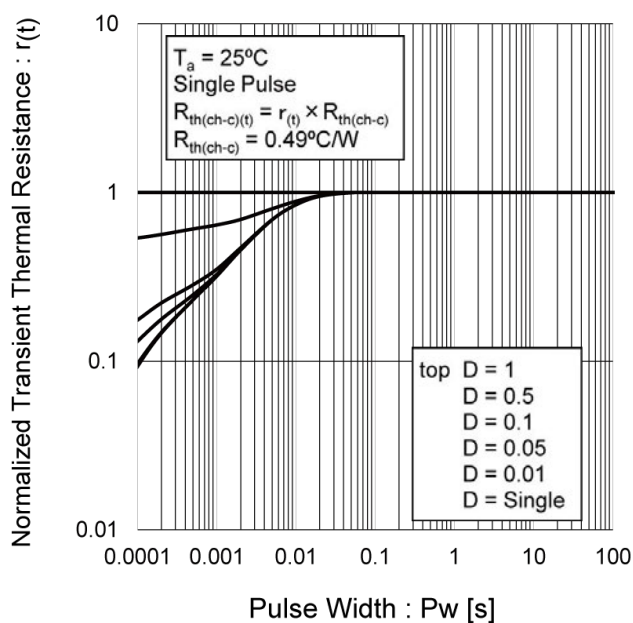
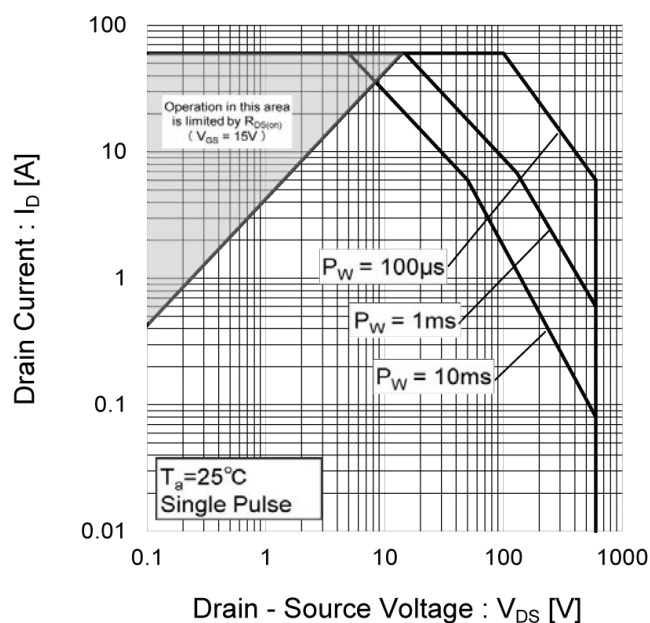


Fig.4 Maximum Safe Operating Area



●Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

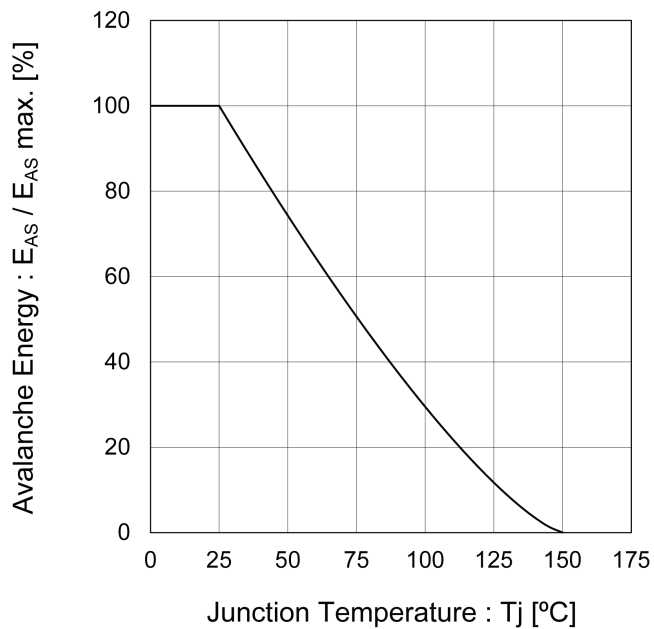


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

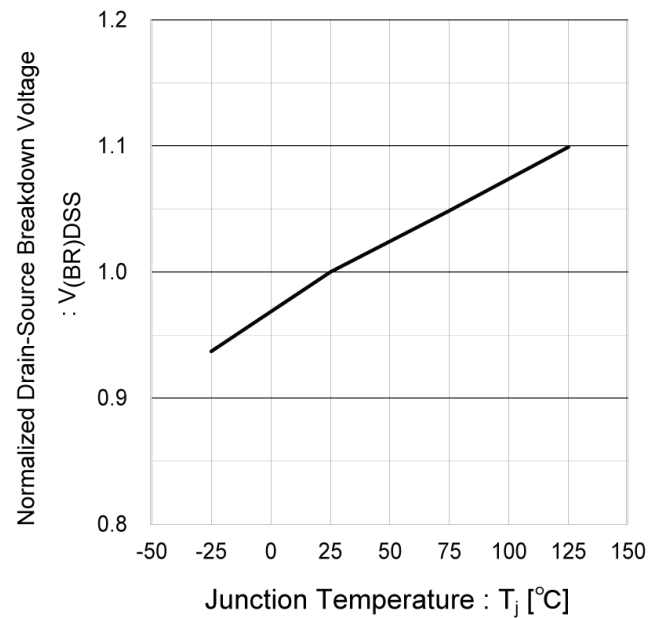


Fig.7 Typical Output Characteristics(I)

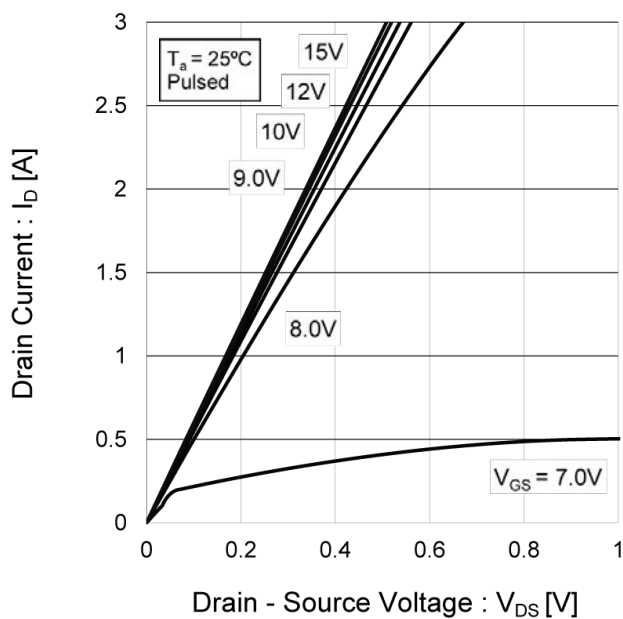
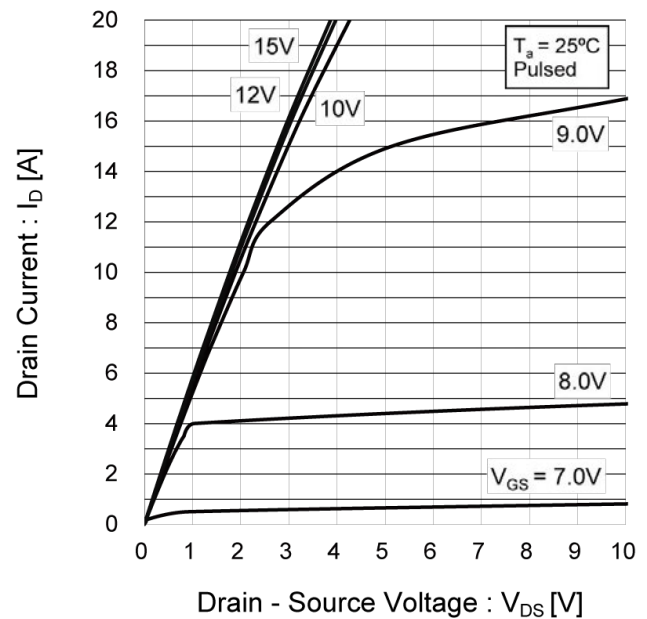


Fig.8 Typical Output Characteristics(II)



●Electrical characteristic curves

Fig.9 Typical Transfer Characteristics

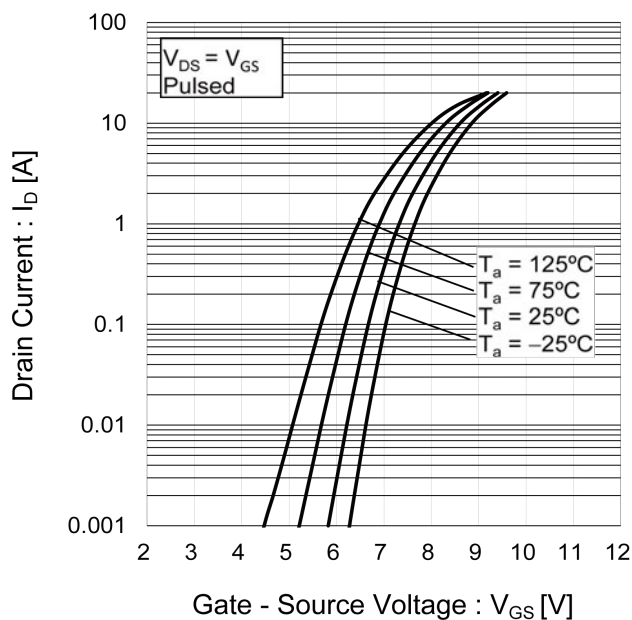


Fig.10 Normalized Gate Threshold Voltage vs Junction Temperature

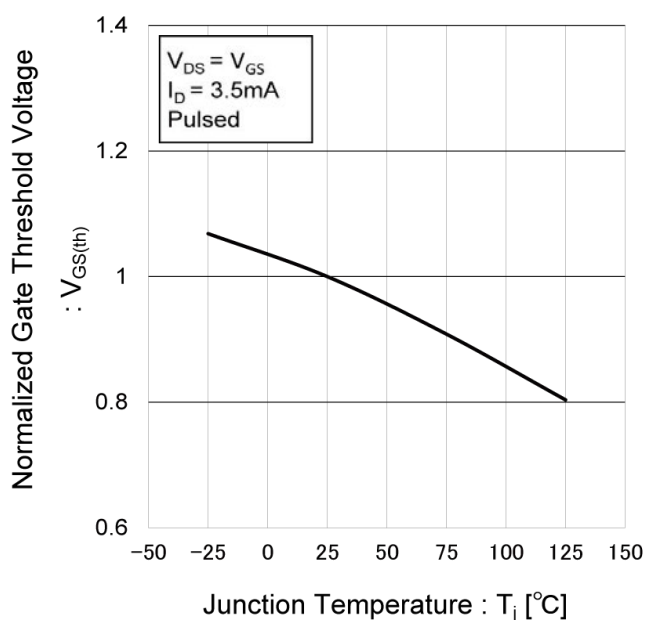


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

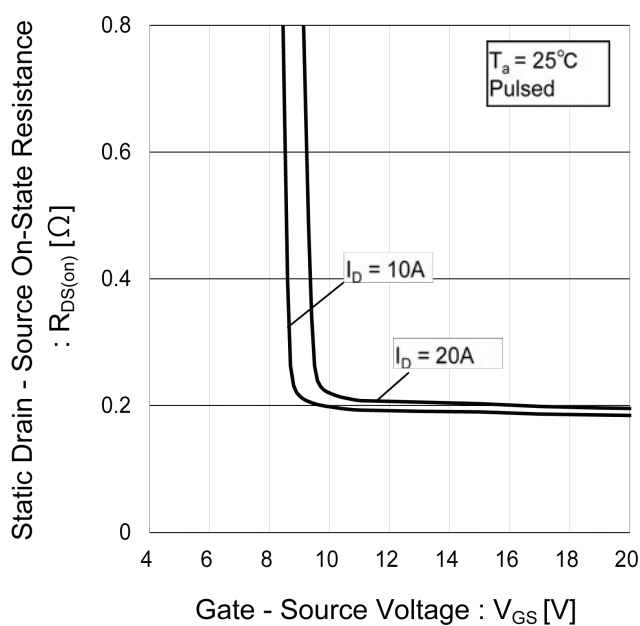
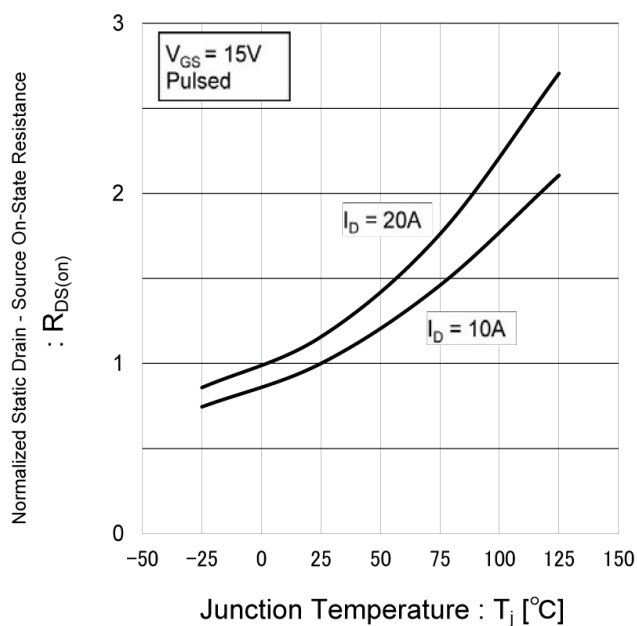


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature



●Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)

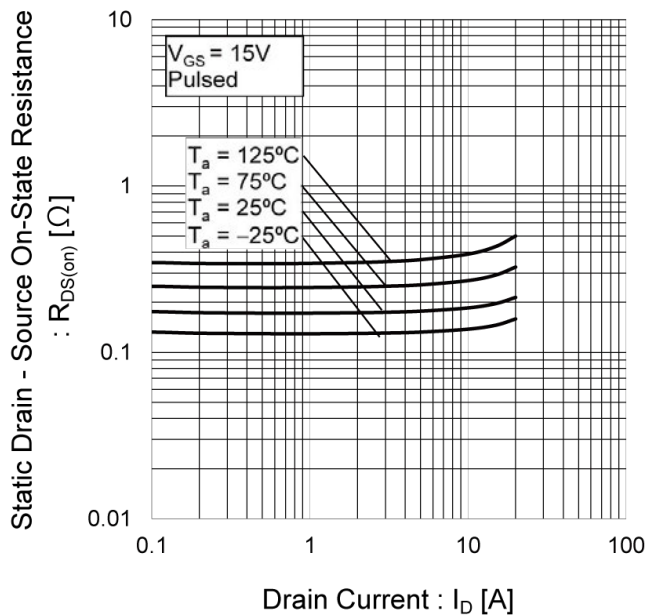


Fig.14 Typical Capacitance vs. Drain - Source Voltage

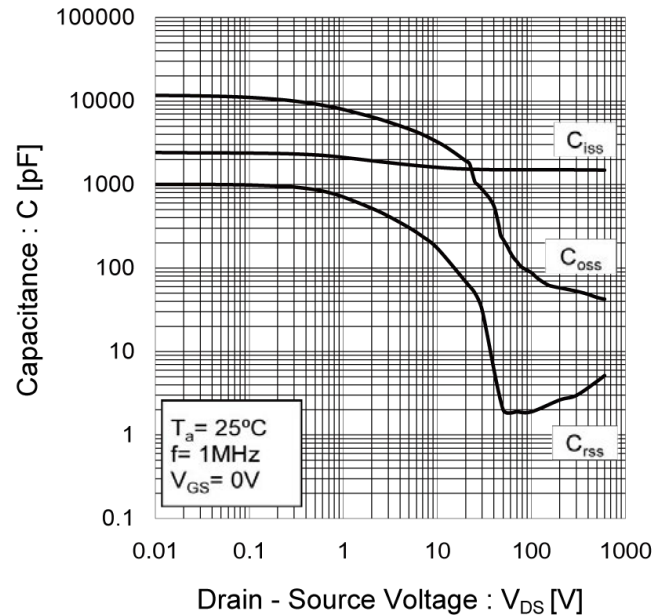


Fig.15 Typical Coss Stored Energy

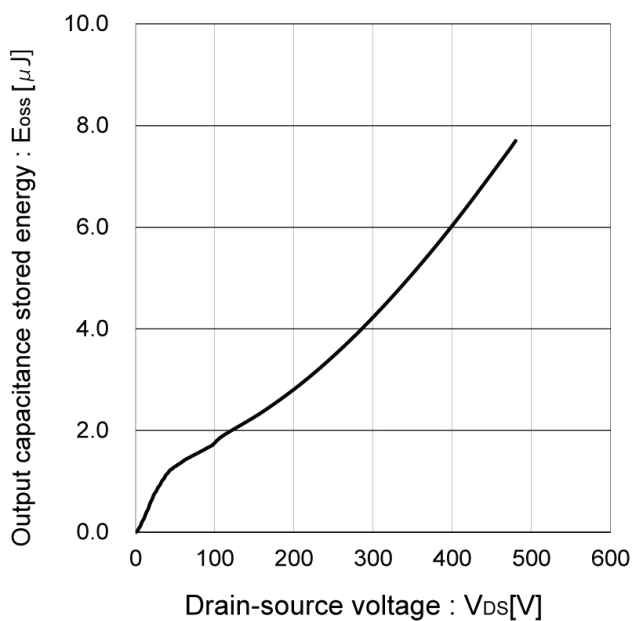
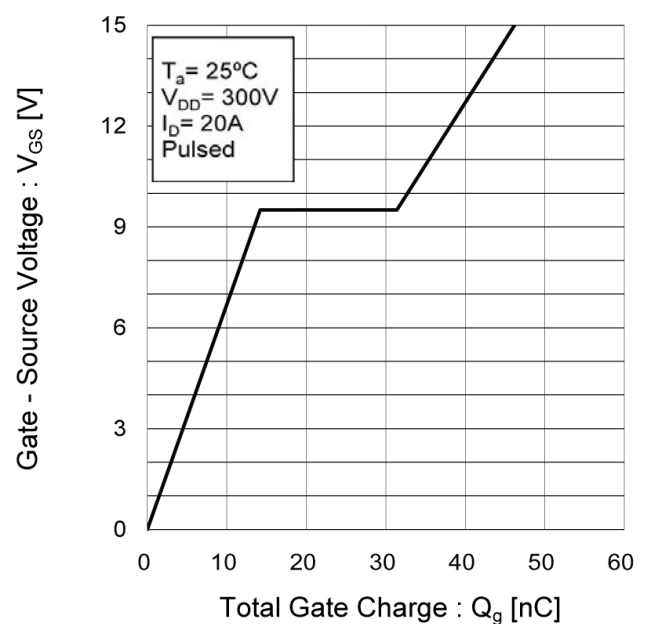


Fig.16 Dynamic Input Characteristics



●Electrical characteristic curves

Fig.17 Inverse Diode Forward Current
vs. Source - Drain Voltage

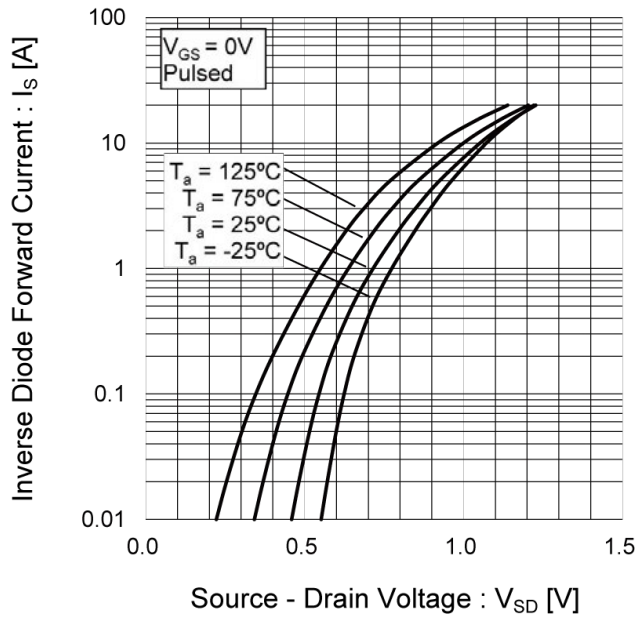
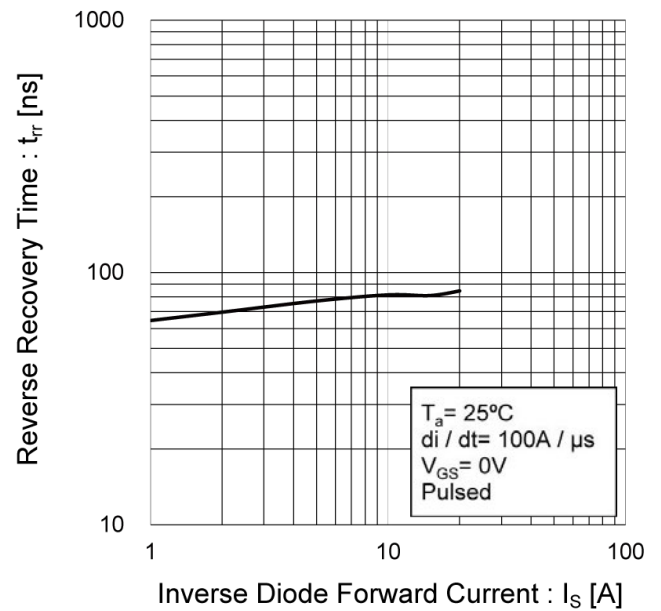


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit



Fig.1-2 Switching Waveforms



Fig.2-1 Gate Charge Measurement Circuit



Fig.2-2 Gate Charge Waveform



Fig.3-1 Avalanche Measurement Circuit



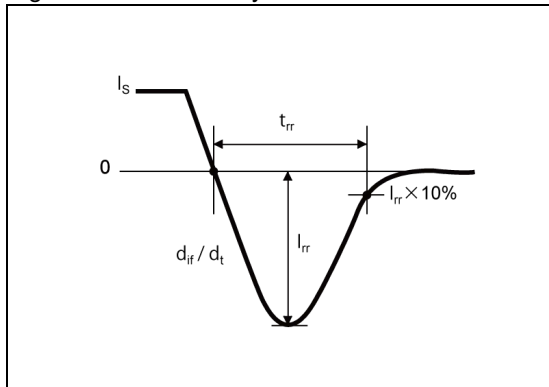
Fig.3-2 Avalanche Waveform



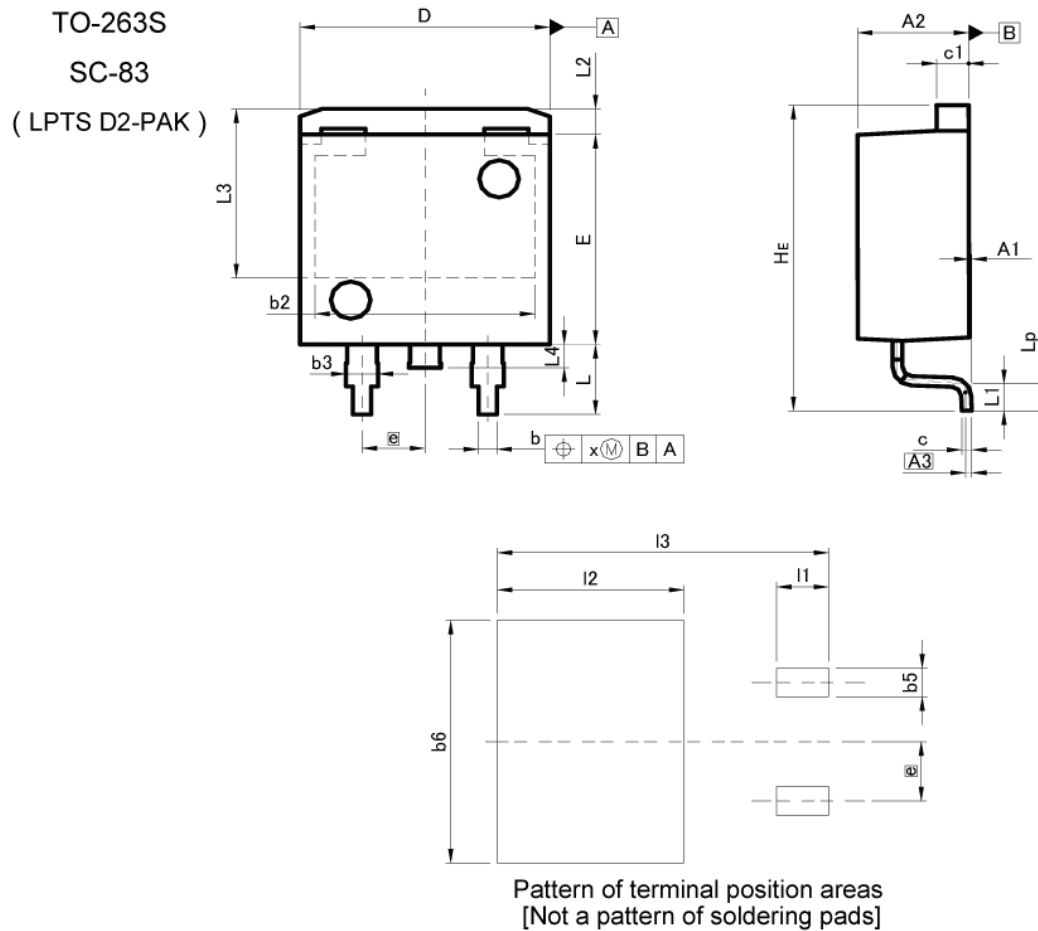
Fig.4-1 Diode Recovery Measurement Circuit



Fig.4-2 Diode Recovery Waveform



●Dimensions



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.25		0.010	
b	0.68	0.98	0.027	0.039
b2	8.90		0.350	
b3	1.14	1.44	0.045	0.057
c	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
e	2.54		0.100	
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.20		0.047	
L2	1.10		0.043	
L3	7.25		0.285	
L4	1.00		0.039	
Lp	0.90	1.50	0.035	0.059
x	-	0.25	-	0.010

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b5	-	1.23	-	0.049
b6	-	10.40	-	0.409
I1	-	2.10	-	0.083
I2	-	7.55	-	0.297
I3	-	13.40	-	0.528

Dimension in mm/inches

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.) ; or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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